

BOURNS®

TBU™ High Speed Protector Products Solder Profile

Lead-Free Reflow Profile Recommendation (IPC/JEDEC J-STD-020C)

Reflow Parameter	Lead-Free Assembly
Average Ramp-up rate (TsMAX to TP)	3°C/second maximum
Minimum preheat temperature (TsMIN)	150°C
Maximum preheat temperature (TsMAX)	200°C
Preheat Time	60-180 seconds
TsMAX to TL ramp-up rate	3°C/second maximum
Time above temperature TL (tL)	217°C 60-150 seconds
Peak Temperature (TP)	260°C
Time 25°C to TP	8 minute maximum
Time within 5° of Peak TP	20-40 seconds
Ramp-down rate	6°C/second maximum

IR/Convection Reflow Profile (IPC/JEDEC J-STD-020C)

